

CMSBN12209-HF

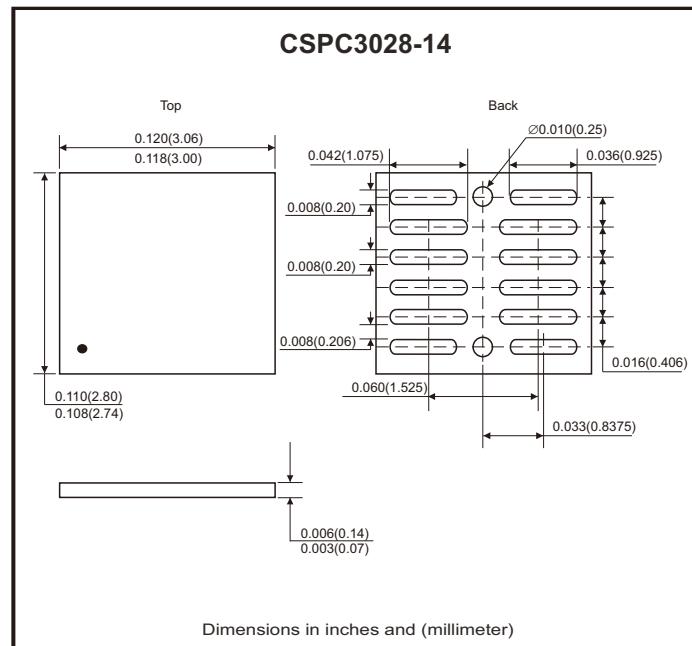
Dual N-Channel
RoHS Device
Halogen Free

Features

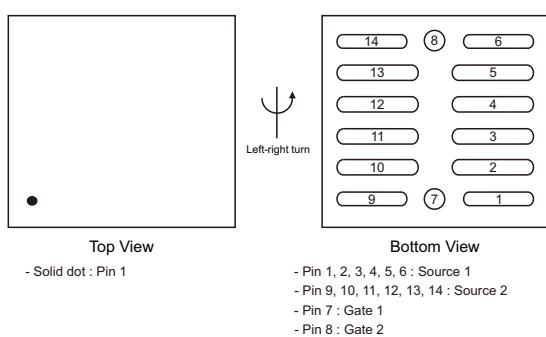
- It is ESD protected.
- This device is suitable for use as a unidirectional or bi-directional load switch, facilitated by its common-drain configuration.

Mechanical data

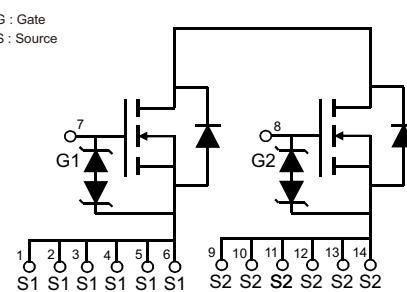
- Case: CSPC3028-14, standard package, molded plastic.



Pin assignment



Circuit diagram



Maximum Ratings (at TA=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Source to source voltage	V _{SSS}	12	V
Gate-source voltage	V _{GSS}	±8	V
Source current DC (Note 1)	I _S	19.8	A
Source current pulse (Note 1, 2)	I _{SP}	198	A
Total dissipation (Note 1)	P _T	3.1	W
Channel temperature	T _{ch}	150	°C
Storage temperature range	T _{TG}	-55 to +150	

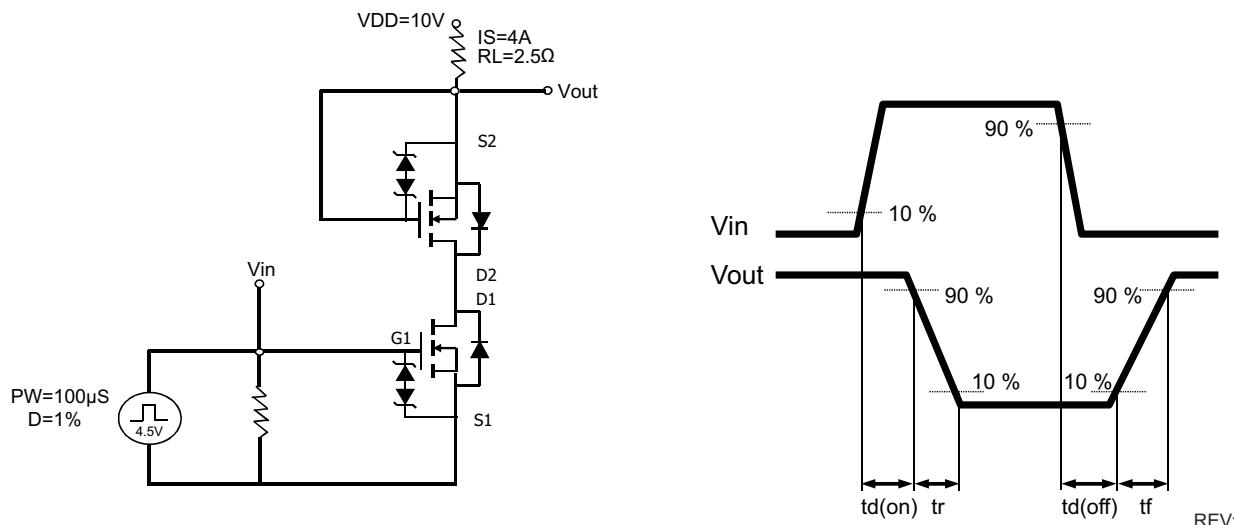
Notes: 1. Mounted on FR4 board (25.4mm x 25.4mm x t1.0mm) using the minimum recommended pad size (36μm copper).

2. t = 10ms, duty cycle = 1 %

Electrical Characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Static parameters						
Source to source breakdown voltage	BV_{SS}	$I_S = 1\text{mA}, V_{GS} = 0\text{V}$	12			V
Zero-gate voltage source current	I_{SS}	$V_{SS} = 10\text{V}, V_{GS} = 0\text{V}$			1	μA
Gate to source leakage current	I_{GS}	$V_{SS} = 0\text{V}, V_{GS} = \pm 8\text{V}$			± 10	μA
Gate to source threshold voltage	V_{TH}	$V_{S2S1} = 6\text{V}, I_S = 2.3\text{mA}$ $V_{S1S2} = 6\text{V}, I_S = 2.3\text{mA}$	0.35	0.77	1.4	V
Source to source on-state resistance	$R_{SS(on)}$	$V_{GS} = 4.5\text{V}, I_S = 3\text{A}$ $V_{GS} = 3.8\text{V}, I_S = 3\text{A}$ $V_{GS} = 3.1\text{V}, I_S = 3\text{A}$ $V_{GS} = 2.5\text{V}, I_S = 3\text{A}$	0.8 0.9 1.0 1.1	1.2 1.3 1.4 1.6	1.56 1.69 1.82 3.20	$\text{m}\Omega$
Input capacitance	C_{iss}	$V_{SS} = 10\text{V}, V_{GS} = 0\text{V}, f = 1\text{kHz}$			6315	pF
Output capacitance	C_{oss}				1393	
Reverse transfer capacitance	C_{rss}				1106	
Turn-on delay time (Note 3)	$t_{d(on)}$	$V_{DD} = 10\text{V}, I_S = 4\text{A}, V_{GS} = 4.5\text{V}$			1.2	μs
Turn-on rise time (Note 3)	t_r				5.7	
Turn-off delay time (Note 3)	$t_{d(off)}$				11	
Turn-off fall time (Note 3)	t_f				15.4	
Total gate charge (Note 3)	Q_g	$V_{SS} = 10\text{V}, I_S = 10\text{A}, V_{GS} = 4.5\text{V}$			75	nC
Gate1-source1 charge (Note 3)	Q_{g1s1}				15	
Gate1-source2 charge (Note 3)	Q_{g1s2}				36	
Diode forward voltage	$V_{F(S-S)}$	$V_{G1S1} = 0\text{V}, V_{G2S2} = 4.5\text{V}, I_S = 3\text{A}$ $V_{G1S1} = 4.5\text{V}, V_{G2S2} = 0\text{V}, I_S = 3\text{A}$			1.0	V

Notes: 3. When FET1 is measured, G2 and S2 are short-circuited.



CSP Enhancement Mode Power MOSFET

Comchip
SMD Diode Specialist

Rating and Characteristic Curves (CMSBN12209-HF)

Fig.1 - I_s — V_{ss}

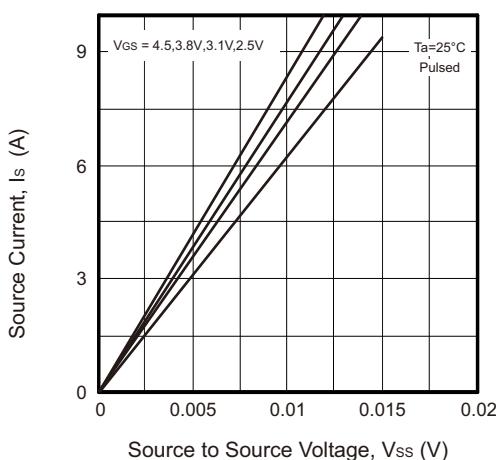


Fig.2 - I_s — V_{gs}

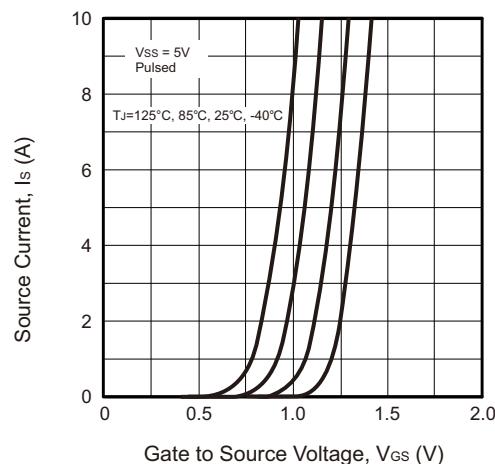


Fig.3 - $R_{SS(on)}$ — I_s

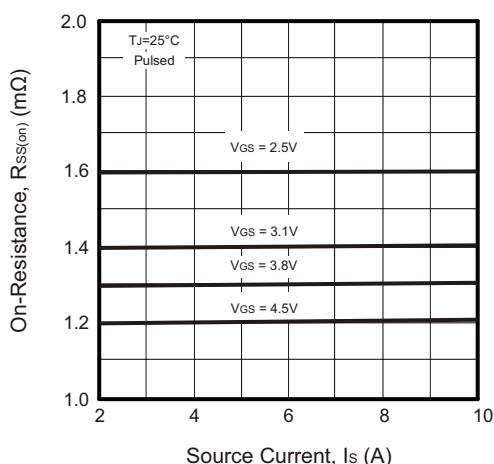


Fig.4 - $R_{SS(on)}$ — V_{gs}

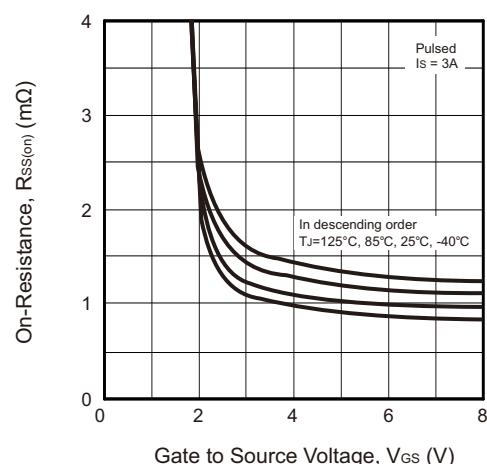


Fig.5 - I_F — V_F

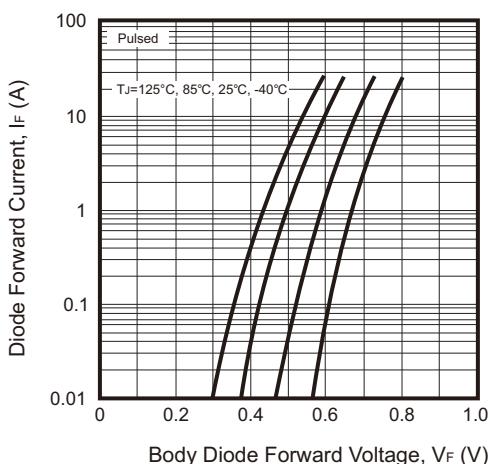
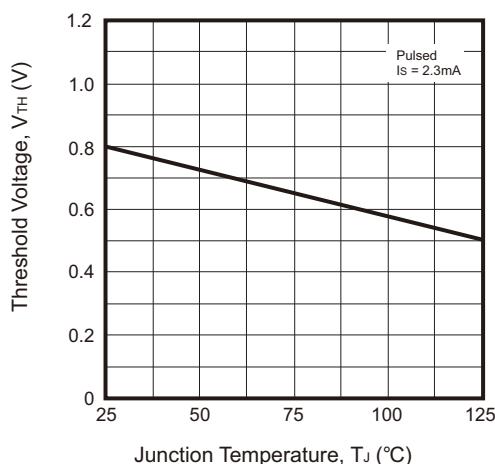


Fig.8 - Threshold Voltage



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Fig.7 - Capacitance

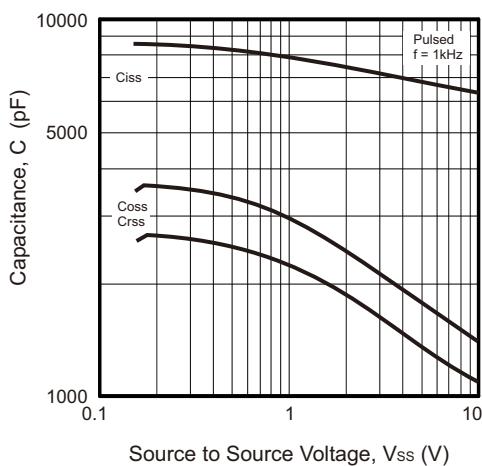


Fig.8 - Gate Charge

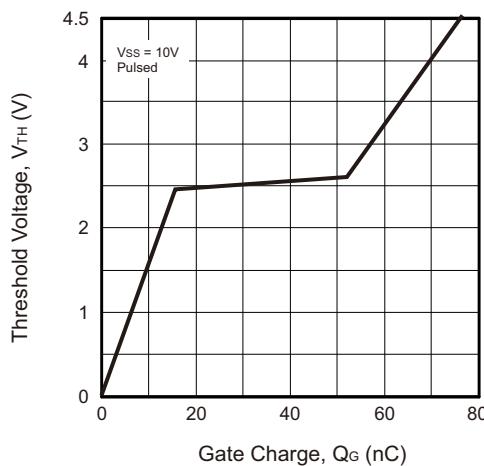


Fig.9 - Normalized Transient Thermal Impedance

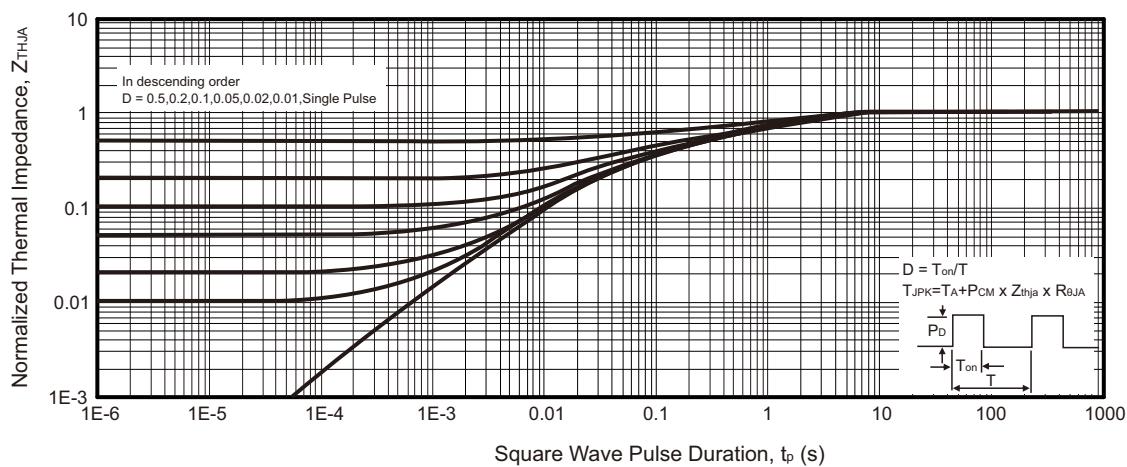


Fig.10 - Maximum Forward Biased Safe Operating Area

